

**8K × 8 Bit Electrically Erasable PROM**

**FEATURES**

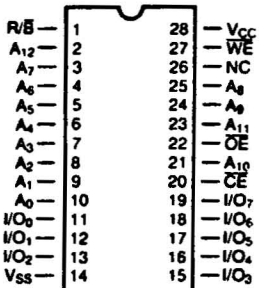
- **Fast Read Access Time:**  
250ns
- **5 Volt-Only Operation - Including Write**
- **Fast Nonvolatile Write Cycle:**  
10ms Max.
  - Automatic Write Timeout
  - Internally Latched Data
  - Internally Latched Address
  - Automatic Erase Before Write
  - DATA Polling Status Indicator
  - READY/BUSY Pin Status Indicator
- **Automatic Page Write**  
- 1 to 32 Bytes in 10ms Max.
- **On-Chip False Write Protection**
- **TTL Compatible Inputs and Outputs**
- **10,000 Rewrites per Byte**
- **10 Year Data Retention**
- **JEDEC Approved Byte Wide Memory Pinout**

write cycle timing very similar to that of a static RAM. The internally self-timed nonvolatile write cycle latches both address and data to provide a free system bus during the write period. The XL2865A incorporates an automatic and transparent byte erase cycle in its byte write operation, completing the erase/write cycle in a maximum of 10ms.

The device is exceptionally system friendly, incorporating two device status indicators and a fully automatic 32-byte page write feature. The two separate status indicators, DATA polling and a READY/BUSY pin, are provided to maximize device versatility and allow the host

The XL2865A is a full featured 8,192 × 8 bit electrically erasable programmable read only memory (E<sup>2</sup>PROM). It is remarkably easy to use, operating from a single 5-volt power supply and utilizing read and

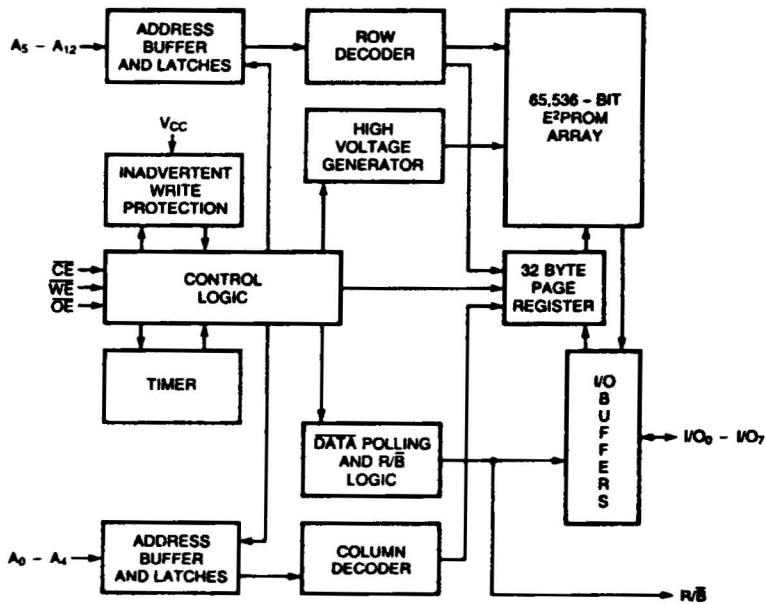
**PIN CONFIGURATION**



**PIN NAMES**

A <sub>0</sub> - A <sub>12</sub>	ADDRESS INPUTS
I/O <sub>0</sub> - I/O <sub>7</sub>	DATA INPUTS/OUTPUTS
CE	CHIP ENABLE
OE	OUTPUT ENABLE
WE	WRITE ENABLE
R/B	READY/BUSY INDICATOR
NC	NO CONNECT
V <sub>CC</sub>	+5V
V <sub>SS</sub>	GROUND

**BLOCK DIAGRAM**



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system to exploit the actual non-volatile write cycle time. DATA polling is a software technique which is used to observe nonvolatile write cycle completion without requiring external hardware. READY/BUSY is an alternate approach which dedicates pin 1 to signal device status and is especially useful in interrupt-driven systems.

The automatic page write feature allows the system to program up to 32 bytes during a single nonvolatile write cycle, providing an effective write speed of at most 312µs/byte. The entire 8K byte memory may be programmed in a maximum of 2.6 seconds when the page write mode is employed.

The XL2865A is the ideal device to use in applications requiring a fast, high density, nonvolatile memory capable of simple in-system modification. Typical applications include robotics, self-calibrating equipment, user programmable firmware, data loggers, security and encryption systems, and remotely reprogrammable machinery.

## DEVICE OPERATION

### Read Cycle

Data is read from the XL2865A as simply as it is from a static RAM, with WE high and CE and OE low. Since the stored charge which defines the bit state is not affected by read cycles, there is no restriction on the number of times that the XL2865A may be read. Data access times from the last to be asserted of CE, OE, or valid address are specified in the Read Cycle Timing section of this data sheet. The I/O pins remain in a high impedance state whenever OE or CE are high providing a dual line control architecture to eliminate bus contention hazards.

### Write Cycle

The XL2865A is designed for exceptional ease of use, integrating data latches, address latches, a high voltage generator, and fully self-timed control logic on-chip so that it writes like a static RAM. Two distinct write cycles are utilized by the XL2865A: one is the write operation performed

## MODE SELECTION

CE	OE	WE	Mode	I/O	Power
V <sub>IH</sub>	X	X	Standby	High Z	Standby
V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	Read	D <sub>OUT</sub>	Active
V <sub>IL</sub>	V <sub>IH</sub>		Byte Write (WE Controlled)	D <sub>IN</sub>	Active
	V <sub>IH</sub>	V <sub>IL</sub>	Byte Write (CE Controlled)	D <sub>IN</sub>	Active
V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IH</sub>	Read and Write Inhibit	High Z	Active
V <sub>IL</sub>	15V		Chip Erase*	D <sub>IN</sub> = V <sub>IH</sub>	Active

\*Contact EXEL Microelectronics for details on the Chip Erase Mode

by the host system and the second is an internal write operation that programs the E<sup>2</sup>PROM array. In this data sheet the term 'system write cycle' refers to that cycle executed by the system wherein data is written to the XL2865A's internal data latches, while the term 'nonvolatile write cycle' refers to the internal operation wherein data is transferred from these latches into the E<sup>2</sup>PROM array.

During a system write cycle, the address is latched into the internal address latches upon the last falling edge of WE or CE providing that OE is a logic '1'. The first rising edge of WE or CE latches the data into the data latches (see figures 2 and 3).

The nonvolatile write cycle is completed off-line in a fully self-timed operation in two transparent stages. During the first stage, the data then present in the locations to be programmed is erased. The second stage copies the data from the internal latches into the appropriate locations in the E<sup>2</sup>PROM array for nonvolatile storage.

The E<sup>2</sup>PROM memory array is not accessible while the nonvolatile write cycle is in progress. Thus neither a read nor a system write operation should be attempted until the nonvolatile write cycle is completed, except that the device may be polled to determine whether the write cycle is complete (see DATA Polling and READY/BUSY sections).

### Automatic Page Write

The XL2865A contains a 32-byte temporary (volatile) buffer which allows the user to simultaneously program

from one to 32 bytes in a page during a single 10ms (max) nonvolatile write cycle without any special setup or software procedures. This can effectively reduce the byte write time by a factor of 32. The device will begin its nonvolatile write cycle from 300 to 600 µs (t<sub>PL</sub>) after the first system write operation following the completion of a previous nonvolatile write cycle (or power-up). At this point, the device commences a nonvolatile write cycle and copies data from each of the latches which were updated into the designated E<sup>2</sup>PROM locations (see Endurance and Data Retention section). Thus, all bytes to be programmed during an automatic page write cycle must be written into the page buffer within t<sub>PL</sub> minimum to guarantee that they are transferred into the E<sup>2</sup>PROM array.

The 32-byte page into which the data will be written is specified by the most significant bits of the address (A<sub>5</sub>-A<sub>12</sub>) presented during the first system write operation following the completion of a previous nonvolatile write cycle (or power-up). The byte within the specified page is identified by the five least significant bits of the address (A<sub>0</sub>-A<sub>4</sub>) presented during the first and subsequent system write cycles. Bytes may be written into the page in any order. If data is written more than once to the same byte in the temporary buffer during a single page load operation, then the most recently written data will be valid.

If a read operation is attempted during loading of the page buffer, the buffer load cycle is not affected. However, that read cycle will be interpreted as a DATA polling cycle.

## DATA Polling

DATA polling is a software method of detecting the end of a nonvolatile write cycle. This is accomplished by allowing the system to monitor the device status via system busses using a simple read and compare operation.

DATA polling does not require any external hardware. During the nonvolatile write cycle the most significant bit of the last byte written to the XL2865A is inverted and routed to the output buffer. The I/O pins remain in a high impedance state unless a read command is issued to the device by the system. In this event, an inverted most significant bit will be available at I/O<sub>7</sub> (I/O<sub>0</sub>-I/O<sub>6</sub> are indeterminate) and, consequently, a comparison of bit 7 of the data read from the XL2865A with bit 7 of the last byte written will indicate unequal values. Once the nonvolatile write cycle is completed, the true data will be accessed with a normal read command.

## READY/ $\overline{\text{BUSY}}$ Pin

The R/ $\overline{\text{B}}$  pin (pin 1) is a dedicated device status indicator which remains at a logic '1' during device operation unless the XL2865A is internally occupied with a nonvolatile write cycle or the supply voltage is below 4.0V (see V<sub>CC</sub> Level Detection). When a system write cycle is initiated, R/ $\overline{\text{B}}$  is brought to a logic '0', returning to a logic '1' when the corresponding nonvolatile write cycle is completed. This pin may be conveniently polled for nonvolatile write cycle status or may be used to initiate an interrupt announcing to the controller that the cycle is complete and the device is, once again, available for normal access. This output is configured as an open-drain driver to allow two or more R/ $\overline{\text{B}}$  outputs to be OR-tied and thus requires an appropriate pull-up resistor for proper operation. The pull-up resistor value for the R/ $\overline{\text{B}}$  output may be calculated as follows:

$$R_p = \frac{5.1V}{I_{IL} + 2.1mA}$$

where  $I_{IL}$  = the sum of the input currents of all devices tied to R/ $\overline{\text{B}}$ .

## False Write Protection

Three mechanisms are designed into the XL2865A to protect the device from inadvertent write commands during power supply transitions and system noise periods.

## V<sub>CC</sub> Level Detection

A sensor on-board the XL2865A monitors the supply voltage level and disables the internal write circuitry whenever V<sub>CC</sub> is less than 4.0V (V<sub>WI</sub>). This serves to protect the data integrity while allowing the device to tolerate an erratic control bus during power transitions, brownouts and blackouts. While V<sub>CC</sub> is below this threshold level (and above 1.0V) R/ $\overline{\text{B}}$  outputs V<sub>IL</sub>.

## Noise Protected $\overline{\text{WE}}$

A noise filter designed into the  $\overline{\text{WE}}$  input ensures that a write pulse of less than 20ns duration will not activate a write cycle.

## Write Inhibit Logic

Logical inadvertent write protection is provided to the system by ensuring that the application of a logic '0' to  $\overline{\text{OE}}$  or a logic '1' to  $\overline{\text{CE}}$  or  $\overline{\text{WE}}$  will inhibit the device's internal write circuitry.

## Chip Erase

All data in the XL2865A can be erased by bringing  $\overline{\text{OE}}$  to 15V while simultaneously bringing  $\overline{\text{WE}}$  low and holding all data inputs high. Following the erase cycle all storage locations will contain a logic '1'. (Please contact EXEL for details.)

## Standby

Power consumption may be reduced by approximately 55% by deselecting the device with a logic '1' applied to  $\overline{\text{CE}}$ .

## Endurance and Data Retention

The XL2865A is designed for applications requiring up to 10,000 rewrites per E<sup>2</sup>PROM byte and ten years of secure data retention. This means that each byte may be reliably rewritten 10<sup>4</sup> times without degrading device operation, and that data will remain valid after the last rewrite for ten years with or without power applied.

The latches in the automatic page write buffer include corresponding flag bits which are set when a given latch is written. In the event that a nonvolatile write cycle occurs with less than 32 bytes of data, only those bytes in the E<sup>2</sup>PROM array corresponding to the locations in the buffer which were actually written will be reprogrammed. This feature eliminates unnecessary cycling and ensures maximum endurance. This is in contrast to some competing E<sup>2</sup>PROM devices which reprogram the full page of nonvolatile locations independent of the number of page latches actually written to. This wastes cell cycles and may substantially reduce device endurance and, consequently, system reliability.

## ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

Temperature Under Bias .....	-55°C to +125°C
Storage Temperature .....	-65°C to +125°C
Voltage on any Pin with Respect to Ground (Except $\overline{OE}$ ) <sup>2</sup> ...	-1.0V to +6.0V
Voltage on $\overline{OE}$ Pin with Respect to Ground <sup>2</sup> .....	-1.0V to +22.0V
DC Output Current .....	-5mA

## Operating Range

Range	Ambient Temperature
Standard	0°C to 75°C
Military	-55°C to +125°C

## DC OPERATING CHARACTERISTICS

Over Operating Range,  $V_{CC} = 5V \pm 5\%$  for standard versions,  $V_{CC} = 5V \pm 10\%$  for *I/O* versions.

Symbol	Parameter	Limits		Units	Test Conditions
		Min.	Max.		
$V_{IL}$	Input Low Voltage	-0.5	0.8	V	
$V_{IH}$	Input High Voltage	2.0	$V_{CC}+0.5$	V	
$V_{OL}$	Output Low Voltage		0.4	V	$I_{OL} = 2.1mA$
$V_{OH}$	Output High Voltage	2.4		V	$I_{OH} = -400\mu A$
$V_{WI}$	$V_{CC}$ Voltage for Write Inhibit	4.0	4.5	V	
$I_{LI}$	Input Leakage Current		10	$\mu A$	$V_{IN} = 0$ to 5.5V
$I_{LO}$	Output Leakage Current		$\pm 10$	$\mu A$	$V_{OUT} = 0$ to 5.5V
$I_{CC}$	$V_{CC}$ Current — Active		110	mA	$\overline{CE} = \overline{OE} = V_{IL}$ ; All I/Os open; Other Inputs = 5.5V
$I_{SB}$	$V_{CC}$ Current — Standby		50	mA	$\overline{CE} = V_{IH}$ ; $\overline{OE} = V_{IL}$ ; All I/Os open; Other Inputs = 5.5V

## CAPACITANCE

$T_A = +25^\circ C$ ,  $f = 1.0$  MHz,  $V_{CC} = 5V$

Symbol	Parameter	Limits		Units	Test Conditions
		Min.	Max.		
$C_{IO}$	Input/Output Capacitance		10	pF	$V_{IO} = 0V$
$C_{IN}$	Input Capacitance		10	pF	$V_{IN} = 0V$

### Notes:

- Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and the functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- This product includes circuitry specifically designed for the protection of its internal devices from damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying any voltages higher than the rated maxima.
- AC conditions of test:  
 Input Pulse Levels                    0.45V to 2.4V  
 Input Rise and Fall Times            $\leq 20$  nsec  
 Timing Reference Levels            0.8V and 2.0V  
 Output Load                            1 TTL Gate and  $C_L = 100$  pF
- This parameter also defines the minimum time that  $\overline{CE}$  and  $\overline{WE}$  must be asserted simultaneously in order to ensure that the write cycle occurs.
- $\overline{WE}$  is noise protected. A write pulse of less than 20ns duration will not activate a write cycle.
- There is no intrinsic value for this parameter, i.e.,  $\overline{CE}$  and  $\overline{WE}$  may be asserted indefinitely. However, if both  $\overline{CE}$  and  $\overline{WE}$  are asserted upon the expiration of  $t_{PL}$ , then the input data currently present will be automatically latched into the addressed buffer and the nonvolatile write portion of the cycle will commence.
- DATA Poling: DATA lines go to Low-Z, with  $\overline{DATA}$  out on  $I/O_7$ , for  $\overline{CE} = \overline{OE} = V_{IL}$ ,  $\overline{WE} = V_{IH}$ .
- This timing diagram shows the storage of two bytes of data. One to 32 bytes may be loaded in a single write cycle. (See Automatic Page Write section.)

## AC CHARACTERISTICS <sup>3</sup>

Over Operating Range,  $V_{CC} = 5V \pm 5\%$  for standard versions,  $V_{CC} = 5V \pm 10\%$  for /V0 versions.

Read Cycle - See Figure 1.

Symbol	Parameter	XL2865A-250 Limits		XL2865A-300 Limits		XL2865A-350 Limits		XL2865A-450 Limits		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
$t_{RC}$	Read Cycle Time	250		300		350		450		ns
$t_{AA}$	Address Access Time		250		300		350		450	ns
$t_{CE}$	Chip Enable Access Time		250		300		350		450	ns
$t_{OE}$	Output Enable Access Time		80		80		120		150	ns
$t_{LZ}$	Chip Enable to Output in Low Z	10		10		10		10		ns
$t_{HZ}$	Chip Disable to Output in High Z	10	80	10	80	10	100	10	100	ns
$t_{OLZ}$	Output Enable to Output in Low Z	10		10		10		10		ns
$t_{OHZ}$	Output Disable to Output in High Z	10	80	10	80	10	100	10	100	ns
$t_{OH}$	Output Hold from Address Change	20		20		20		20		ns

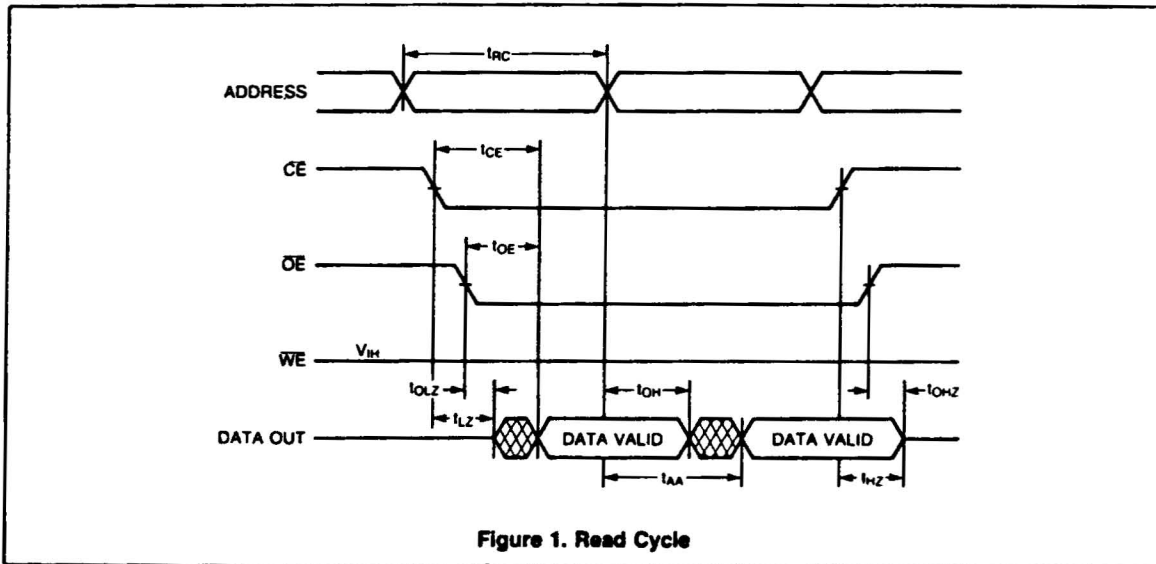


Figure 1. Read Cycle

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Write Cycle - See Figures 2 and 3.

Symbol	Parameter	Limits		Units
		Min.	Max.	
$t_{NW}$	Nonvolatile Write Time		10	ms
$t_{AS}$	Address Setup Time	10		ns
$t_{AH}$	Address Hold Time	125		ns
$t_{CS}$	Chip Enable or Write Setup Time	0		ns
$t_{CH}$	Chip Enable or Write Hold Time	0		ns
$t_{CW}^4$	Chip Enable Pulse Width	150	Note 6	ns
$t_{OES}$	Output Enable Setup Time	10		ns
$t_{OEH}$	Output Enable Hold Time	10		ns
$t_{WPE}^5$	Write Enable Pulse Width	150	Note 6	ns
$t_{DL}$	Data Latch Time	50		ns
$t_{DS}$	Data Setup Time	50		ns
$t_{DH}$	Data Hold Time	10		ns
$t_{PL}$	Page Load Time	300	600	$\mu$ s
$t_{BP}$	$\overline{CE}$ and $\overline{WE}$ Low to $R/\overline{B}$ Low		150	ns
$t_{BWR}$	Busy to Write Recovery Time	50		ns
$t_{WC}$	Byte Load Cycle	1	25	$\mu$ s

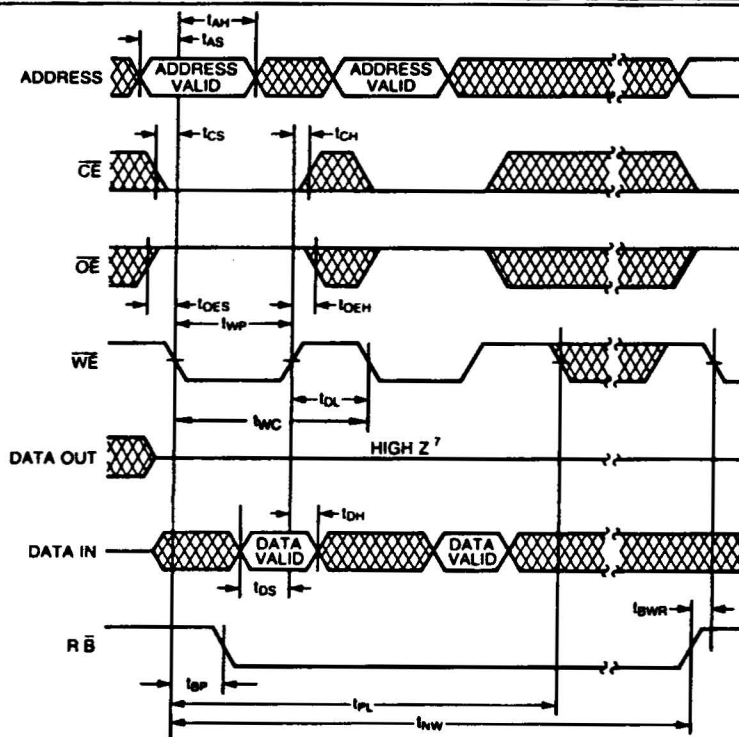
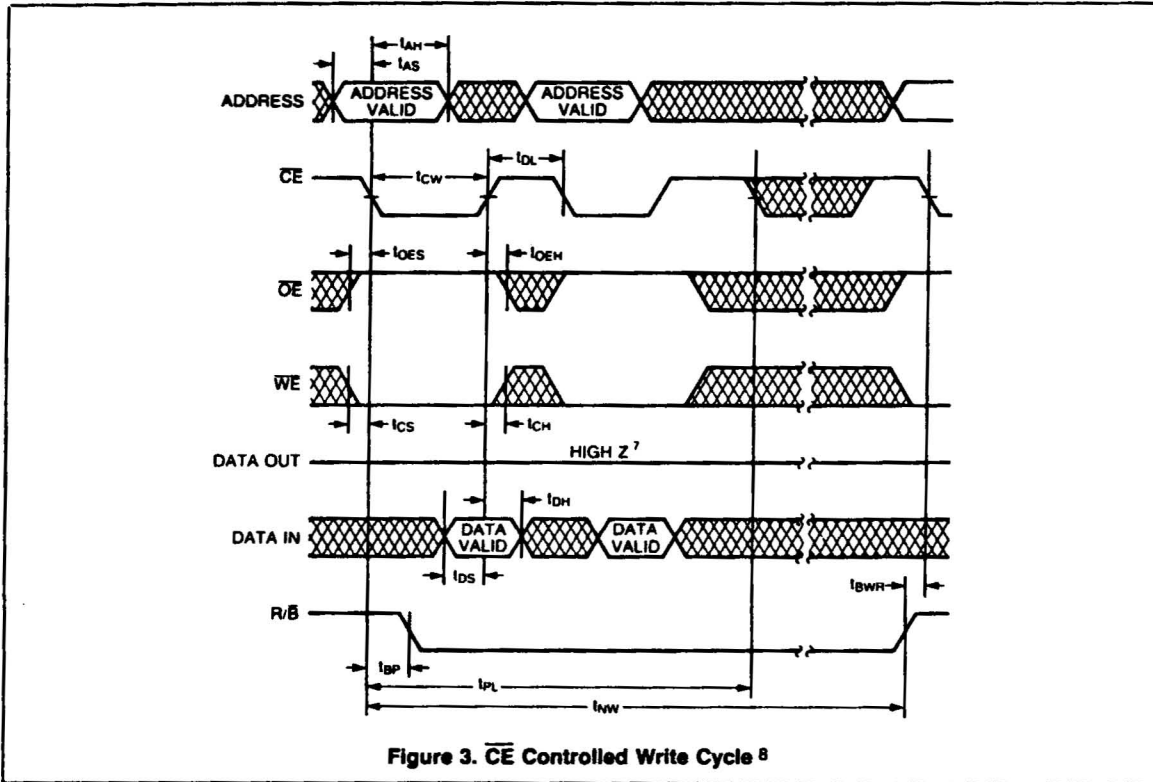


Figure 2.  $\overline{WE}$  Controlled Write Cycle <sup>6</sup>



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**ORDERING INFORMATION**

Part Number	Access Time (ns)	Temperature Range	Operating Supply Variation (V)	Package
XLS2865AC-250	250	0-70°C	4.75-5.25	CERDIP 28 Lead Dual-In-Line
XLS2865AC-300	300			
XLS2865AC-350	350			
XLS2865AC-450	450			
XLS2865AP-250	250	0-70°C	4.75-5.25	PLASTIC 28 Lead Dual-In-Line
XLS2865AP-300	300			
XLS2865AP-350	300			
XLS2865AP-450	450			
XLS2865AC-250/V0	250	0-70°C	4.5-5.5	CERDIP 28 Lead Dual-In-Line
XLS2865AC-300/V0	300			
XLS2865AC-350/V0	350			
XLS2865AC-450/V0	450			
XLS2865AP-250/V0	250	0-70°C	4.5-5.5	PLASTIC 28 Lead Dual-In-Line
XLS2865AP-300/V0	300			
XLS2865AP-350/V0	350			
XLS2865AP-450/V0	450			
XLM2865AC-300	300	-55 +125°C	4.5-5.5	CERDIP 28 Lead Dual In-Line
XLM2865AC-350	350			
XLM2865AC-450	450			